

<b>Notice of References Cited</b>	Application/Control No. 10/710,522	Applicant(s)/Patent Under Reexamination CHEN, CHUNG-CHIH	
	Examiner TabassomT Tadayyon-Eslami	Art Unit 1709	Page 1 of 1

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	L	US-			
	M	US-			

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**NON-PATENT DOCUMENTS**

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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